# **MA3X787** (MA787)

## Silicon epitaxial planar type

For super high speed switching For small current rectification

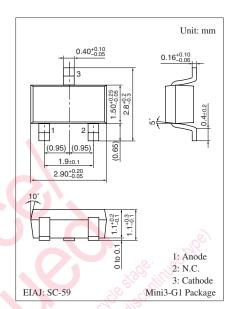
### ■ Features

- Forward current (Average)  $I_{F(AV)} = 100$  mA rectification is possible
- Optimum for high frequency rectification because of its short reverse recovery time t<sub>rr</sub>
- Low forward voltage V<sub>F</sub> and good rectification efficiency
- Reverse voltage  $V_R = 50 \text{ V}$  is guaranteed

### ■ Absolute Maximum Ratings T<sub>a</sub> = 25°C

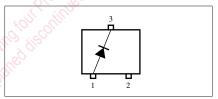
Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	50	V
Repetitive peak reverse voltage	V <sub>RRM</sub>	50	V
Peak forward current	$I_{FM}$	300	mA
Forward current (Average)	I <sub>F(AV)</sub>	100	mA
Non-repetitive peak forward surge current *	I <sub>FSM</sub>	1	A
Junction temperature	$T_{j}$	125	°C
Storage temperature	$T_{stg}$	-55 to +125	°C

Note) \*: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)



Marking Symbol: M3U

### Internal Connection

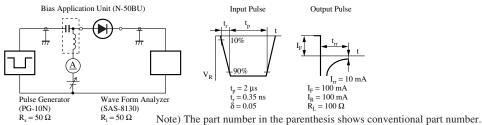


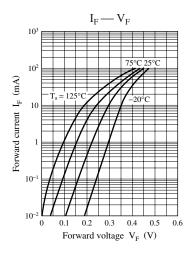
## ■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

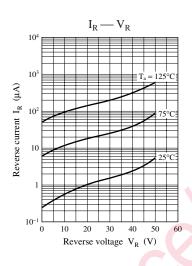
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V <sub>F</sub>	$I_F = 100 \text{ mA}$			0.55	V
Reverse current	I <sub>R</sub>	$V_R = 50 \text{ V}$			30	μΑ
Terminal capacitance	Ct	$V_R = 0 \text{ V, f} = 1 \text{ MHz}$		25		pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = I_R = 100 \text{ mA}$		3.0		ns
	B. Willia	$I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$				

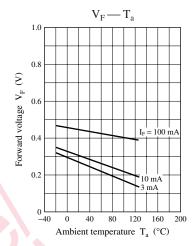
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

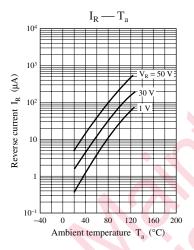
- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 200 MHz.
- 4. \*: t<sub>rr</sub> measurement circuit

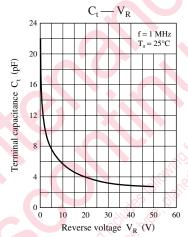












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